



WQFN-HR - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

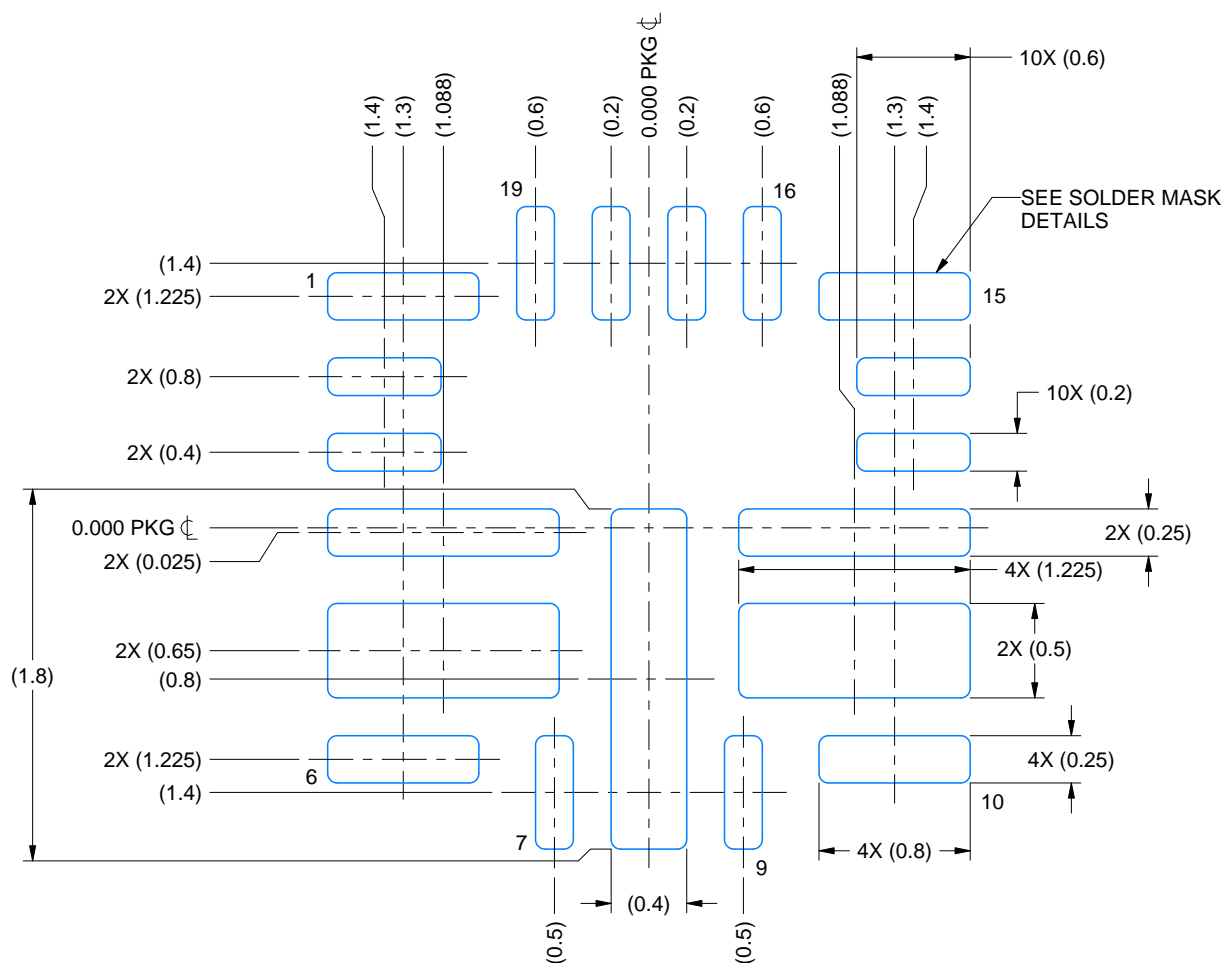
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

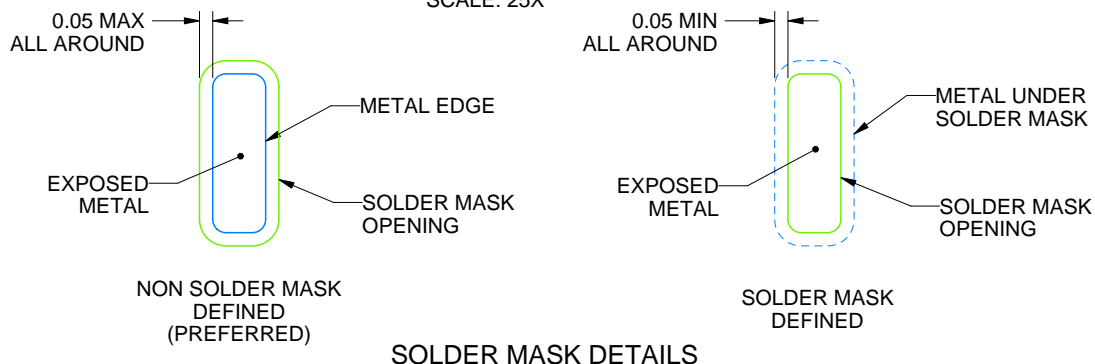
VAN0019A

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LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



4230372/B 04/2025

NOTES: (continued)

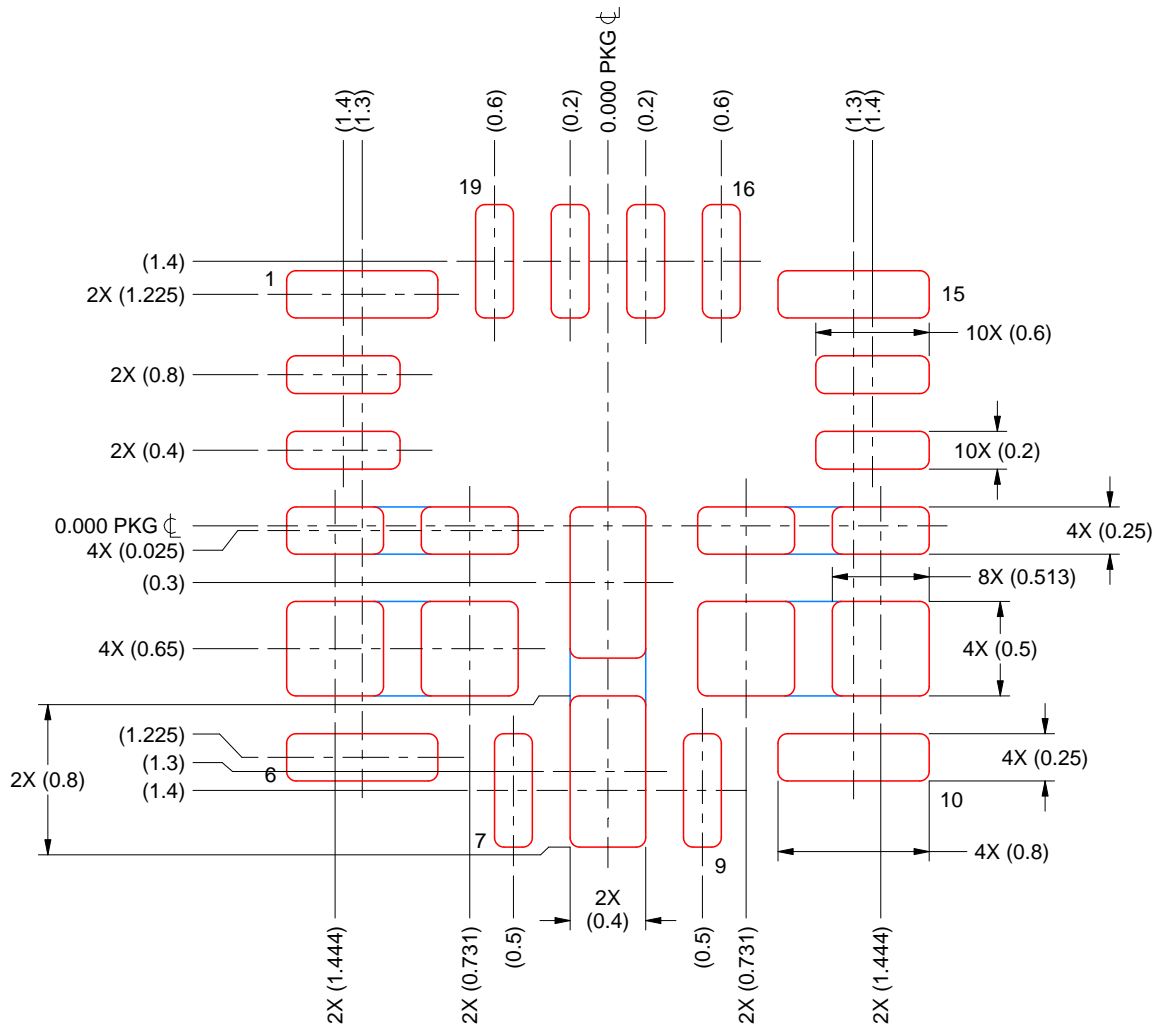
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).

EXAMPLE STENCIL DESIGN

VAN0019A

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SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE: 25X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
 PADS 4, 5, 11 & 12: 84%
 PAD 8: 89%

4230372/B 04/2025

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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